

1 2 3 4 5 6 7 8

A

A

B

B

C

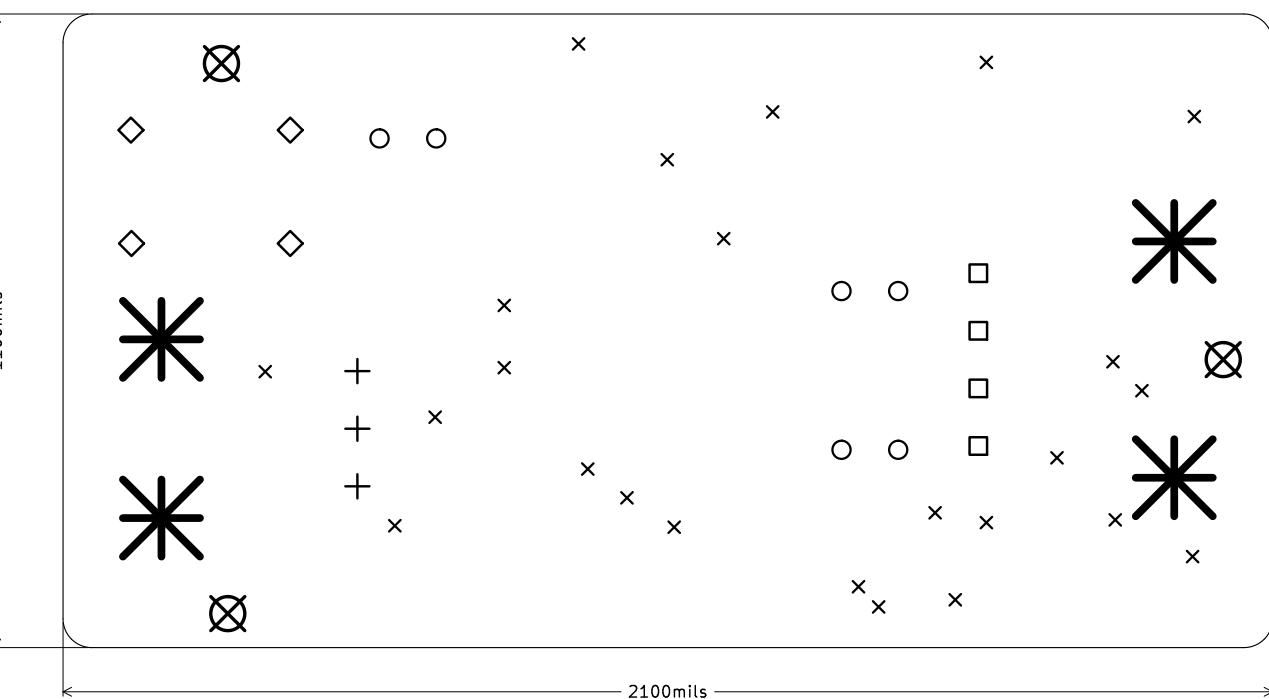
C

D

D

#### BOARD CHARACTERISTICS

Copper Layer Count: 2 Board Thickness: 62.99 mils  
Board overall dimensions: 2100.00 mils x 1100.00 mils  
Min track/spacing: 10.00 mils / 10.00 mils Min hole diameter: 19.69 mils  
Copper Finish: HAL SnPb Impedance Control: No  
Castellated pads: No Plated Board Edge: No  
Edge card connectors: No



Layer Name	Type	Material	Thickness (mils)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mils	Not specified	1	0
F.Paste	Top Solder Paste		0 mils		1	0
F.Mask	Top Solder Mask	Not specified	0.3937 mils	Green	3.3	0
F.Cu	copper		1.37795 mils		1	0
Dielectric	core	FR4	59.44882 mils	Not specified	4.5	0.02
B.Cu	copper		1.37795 mils		1	0
B.Mask	Bottom Solder Mask	Not specified	0.3937 mils	Green	3.3	0
B.Paste	Bottom Solder Paste		0 mils		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mils	Not specified	1	0

Drill Map:  
X 0.508mm / 0.0200" (24 holes)  
O 0.800mm / 0.0315" (6 holes)  
+ 1.067mm / 0.0420" (3 holes)  
□ 1.092mm / 0.0430" (4 holes)  
◊ 1.100mm / 0.0433" (4 holes)  
⊗ 1.500mm / 0.0591" (3 holes) {not plated}  
\* 3.400mm / 0.1339" (4 holes) {not plated}



1868 SPACE COOKIES

Sheet:  
File: BeamBreak-v1.kicad\_pcb

Title: Beam Break Adapter

Size: B Date: 2026-01-04  
KiCad E.D.A. 9.0.7

Rev: 1  
Id: 1/1

1 2 3 4 5 6 7 8